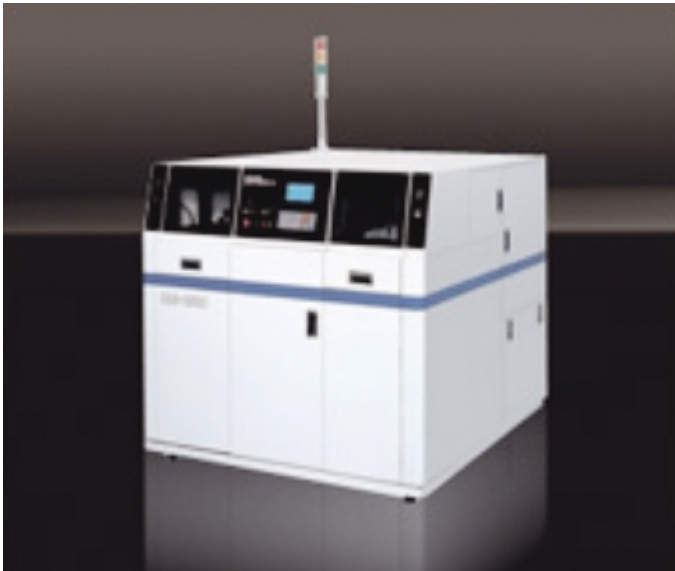


200mm Fully-Automatic Wafer Mounter

RAD-2500F/8



Facility

Power Supply	Voltage	: AC200-230V ±10% (AC190-253V)
	Frequency	: 50/60Hz
	Phase	: single phase
	Power consumption	: 1.0kW
Air Supply	Air pressure	: 0.5-0.8MPa
	Air consumption	: >400L/min (ANR)

Applicable Wafer Size

150mm, 200mm
Please inquire about options for compatibility with specific wafer sizes.

Size

Width : 1,360mm
Depth : 1,512mm
Height : 1,350mm
(excluding the signal tower)

Weight

1,000kg

UPH

100wafers/hour

Outline

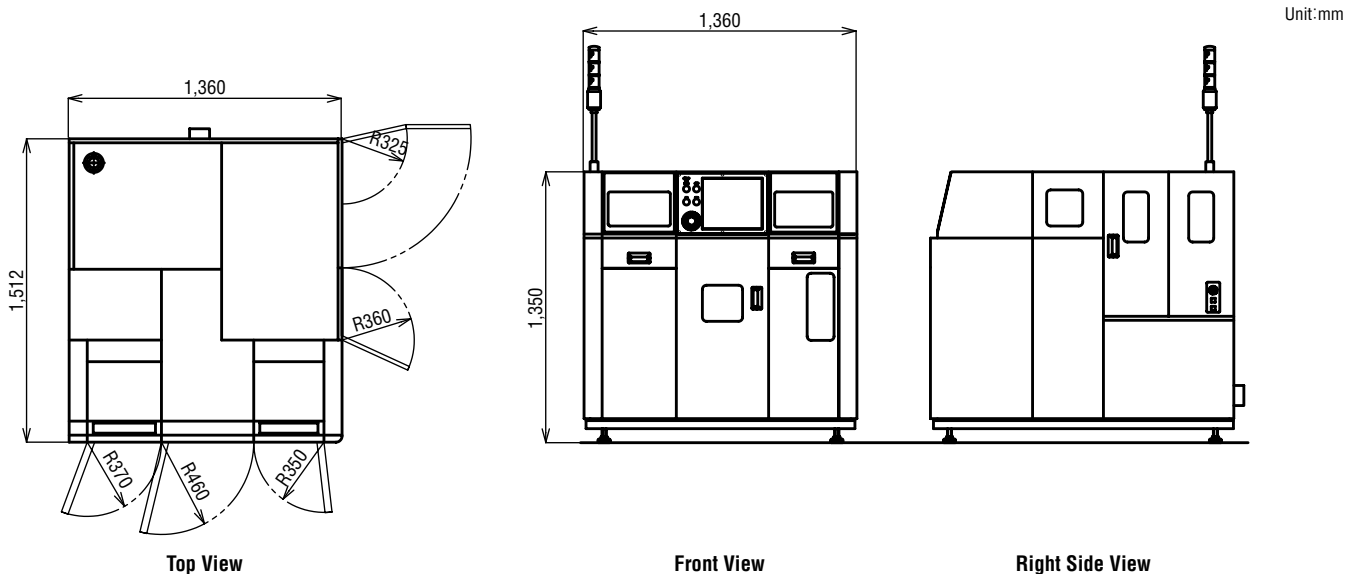
- Fully-automatic wafer mounter for pre-cut dicing tapes.
- Consists of alignment function and TTC* system which reduces voids at lamination.

*TTC (Tape Tension Control) System : The TTC is a cutting-edge system, in which a microcomputer controls tape tension. It enables the tape to be laminated according to the tape type and back-end processing conditions.
On the fully-automatic type, tape application torque and torque curve can be set and registered with the equipment's touch screen.

Option ·Host Communication Function (Communication Format :
Conforms to SECS-I and HSMS/Software : Conforms to GEM)

Suitable Tapes ·Pre-cut dicing tape : Adwill D series, G series
·Dicing die bonding tape : Adwill LE Tape

External View



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